

**Average Weight: 20.7999g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>1.187223</b>	<b>5.708</b>
	Silicon	7440-21-3	100.00		1.187223	
<b>Solder Bump</b>					<b>0.008333</b>	<b>0.040</b>
	Tin	7440-31-5	63.00		0.005250	
	Lead	7439-92-1	37.00		0.003083	
<b>Underfill</b>					<b>0.147000</b>	<b>0.707</b>
	Silica	60676-86-0	70.00		0.102900	
	Epoxy Resin A	9003-36-5	20.00		0.029400	
	Epoxy Resin B	25068-38-6	3.00		0.004410	
	Hardener	19900-65-3	7.00		0.010290	
<b>Heat Sink</b>					<b>13.300000</b>	<b>63.943</b>
	Copper	7440-50-8	99.90		13.286700	
	Nickel	7440-02-0	0.10		0.0133300	
<b>Heat Sink Adhesive</b>					<b>0.085000</b>	<b>0.409</b>
	Silane compound	Proprietary	70.00		0.059500	
	Filler materials	Proprietary	27.00		0.022950	
	Polymetric resin	Proprietary	3.00		0.002550	
<b>Laminate</b>					<b>4.652150</b>	<b>22.366</b>
	Copper	7440-50-8	47.61	Metal layer	2.214911	
	Nickel	7440-02-0	0.51	Metal layer	0.023726	
	Gold	7440-57-5	0.11	Metal layer	0.005117	
	Glass fiber	N/A	10.35		0.481502	
	Halogen fire retardant	N/A	5.25		0.244054	
	BT (core)	N/A	27.54		1.281355	
	Solder mask	N/A	8.63		0.401485	
<b>Solder Balls</b>					<b>1.420156</b>	<b>6.828</b>
	Tin	7440-31-5	95.50		1.356249	
	Silver	7440-22-4	4.00		0.056806	
	Copper	7440-50-8	0.50		0.007101	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
12/20/05	1.0	Initial Xilinx release.
5/03/06	1.1	100% Material Declaration.
9/22/06	1.2	Updated component and substance weights.
7/20/10	1.3	Updated Heat Sink substance description.

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